

Intel® Server Board S7200AP / APL
Intel® Compute Module HNS7200AP / APL
Intel® Server Chassis H2000XXLR2 Family

Product Family Configuration Guide & Spares/Accessories List

A Reference document used to assist with ordering parts and accessories available to configure an Intel server system based on the Intel Server S7200AP product family.

Revision 1.03 May 2018

Intel® Server Boards and Systems

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Document Revision History

Date Published	Revision	Revision Change Description
June 2016	1.0	1 st Production Release
September 2016	1.01	Updated with general availability information
June 2017	1.00	Update node/board weights; update Node Power Spare UPC and ECN; add RMM4 Lite 2; remove mistaken
Julie 2017	1.02	H2216XXKR2 reference; update product images
May 2018	1.03	Corrected references to FH2000NPBAP

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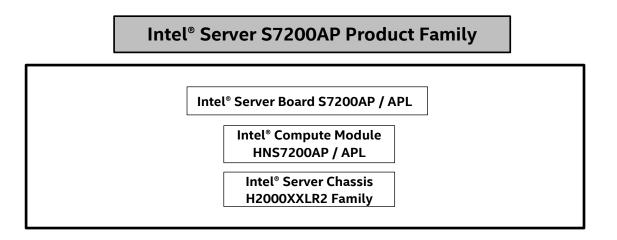
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1. Intel Server Family Overview

This document is provided to assist Intel customers with identifying the right Intel server system and available accessories, enabling them to create a unique server platform that meet their unique server requirements.

The Intel® S7200AP product family consists of the following:



Server Building Blocks:

- Intel® Server Board S7200AP / APL Half width Server Board only (Building block option and spare FRU)
- Intel® Compute Module HNS7200AP / APL Compute module integrated with an Intel® Server Board S7200AP
- Intel® Server Chassis H2000XXLR2 product family 2U four compute module capable rack mount server chassis

The Intel® S7200AP product family supports the following processors and memory:

- Intel® Xeon Phi™ processor (KNL-D-68 Core) with a maximum TDP of 215W
- Intel® Xeon Phi™ processor (KNL-F-68 Core) with integrated Intel® Omni-Path fabric with a maximum TDP of 230W
 - o Note: Previous generation Intel® Xeon® Phi processors are not supported.
- DDR4 (RDIMM & LRDIMM)



Intel® Server Board S7200AP / APL



Intel® Compute Module HNS7200AP / APL

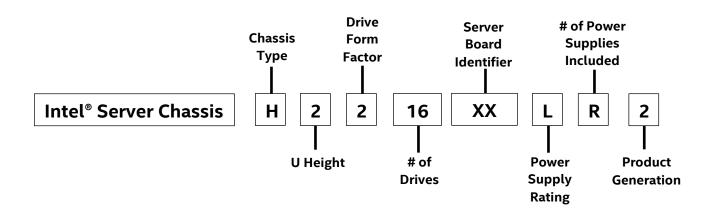


Intel® Server Chassis H2216XXLR2



Intel® Server Chassis H2312XXLR2

1.1 Intel® Server S7200AP Product Family Naming Convention



	Server Board Identifier
Chassis Type	XX – Various Compute Modules Supported
H = Half Width Node Multi-Module	
U Height	Power Supply Rating
2 = 2U	L = 2130W Platinum
Drive Form Factor	# of Power Supplies Included
2 = 2.5"	S = 1 (Single, Non-redundant)
3 = 3.5"	R = 2 (Redundant)
# of Drives Supported	Product Generation
(Specific to front drive bays)	
12	2 = 2nd Generation Product
16	

Table 1. Intel® Server S7200AP Product Family Feature Set

Feature	Description
Processor Support	Intel® Xeon™ Phi™ processor (KNL-D-68 Core)
	 Single processor socket P (3647 pins)
	 Thermal Design Power (TDP) up to 215W
	36 lanes of Integrated PCI Express® 3.0 low-latency I/O
	Intel® Xeon™ Phi™ processor (KNL-F-68 core) with integrated Intel® Omni-Path fabric Single processor socket P (3647 pins) Integrated 4x25 Gb/s Host Fabric Interface Thermal Design Power (TDP) up to 230W
	4 lanes of Integrated PCI Express® 3.0 low-latency I/O
Memory Support	 Six DIMM slots in total across six memory channels Registered DDR4 (RDIMM), Load Reduced DDR4 (LRDIMM) Memory DDR4 data transfer rates of 2133/2400 MT/s 1 DIMM per channel Max memory 384GB
Chipset	Intel C610 "Wellsburg" Platform Controller Hub (PCH)
External I/O Connections	TWO GSB 3.0 COMMECTORS
1515 1110	Two RJ-45 10/100/1000 Mbit Network Interface Controller (NIC) ports
Internal I/O	One USB 2.0 Header TRM Header
connectors/headers	One TPM Header One Install® Open Path I Fall in Single Connection (Option)
	One Intel® Omni-Path I Fabric Signal Connector (Option) One mSATA Connector
	- One mark connector
	One Bridge Board Connector One 3.7 This board of connector
	One 2x7 pin header for system fan module
	One Aux Front Panel Connector Three One in first has done for third party phase in surprant.
	Three 8-pin fan headers for third-party chassis support One 4 pin GPU For an Woter Purpo header.
	One 4 pin CPU Fan or Water Pump header One PSU Control Header
	- One i 30 controt rieadei
	- One Kirili header for litter Kirilia Lite
	- One internat Kob video freader
PCIe Support	One Serial Port A Header PCIo* 3.0 (2.5.5.0 CT/o)
	PCIe* 3.0 (2.5, 5, 8 GT/s)
Power Connections	Two sets of 2x3 pin connector
	One 8 pin Power control connector
	One 4 pin Power connector for Disk Drive power
System Fan Support	 Three 40x56mm double rotor fans
	One 4 pin CPU Fan or Water Pump header
Video	 Integrated 2D video graphics controller
	■ 128MB DDR3 memory

Intel® Server S7200AP Product Family Configuration Guide & Spares/Accessories List

Feature	Description
Riser Support	One PCIe Gen3 x16 standard riser connector
	 Supports a low-profile adapter in Riser slot 1
	 One PCIe Gen3 x20 HSEC-8 fine-pitch riser connector
	 Supports a x16 low-profile adapter in Riser slot 2
	 Supports a x4 low-profile adapter in Riser 2 when fabric is used
On-board storage	■ Integrated 9-port SATA
controllers and options	o 4 ports to bridge board,
	o 1 port to mSATA
	o 4 ports to MiniSAS HD connector
Fabric	 Dual port Intel® Omni-Path Fabric via KNL-F Processor
	or
	Single Port Intel® Omni-Path Fabric via x16 Gen 3 PCIe Adapter
Network (LAN)	■ Dual i210 Springvilles
	■ Dual 10/100/1000Gbe RJ45 connectors
	 NC_SI sideband to BMC. Option to host share or dedicate a Network port to management traffic.
RAID Support	 Intel[®] Embedded Server RAID Technology 2 (ESRT2)
Server Management	Onboard Emulex* Pilot III Controller
	 Support for Intel® Remote Management Module 4 Lite solutions
	Support for Intel® System Management Software
	 Support for Intel[®] Intelligent Power Node Manager (Need PMBus*-compliant power supply)

Table 2. Intel® Compute Module HNS7200AP Feature Set

Feature ¹	Description
Server Board	Intel® Server Board S7200AP product family
	Intel® Xeon™ Phi™ processor (KNL-D-68 Core)
	 Intel® Xeon™ Phi™ processor (KNL-D-68 Core)
	Intel® Xeon™ Phi™ processor (KNL-F-68 Core) with integrated Intel® Omni-Path
	fabric
Processor Support	Maximum supported Thermal Design Power (TDP) of up to 230W
Heatsink	One 80x107mm 1U Heatsink
Fan	Three 40x56mm dual rotor system fans
Riser Support	One PCIe Gen3 x16 standard riser connector
	 Supports a low-profile adapter in Riser slot 1
	One PCIe Gen3 x20 HSEC-8 fine-pitch riser connector
	 Supports a x16 low-profile adapter in Riser slot 2
	Supports a x4 low-profile adapter in Riser 2 when fabric is used
Compute Module Board	Bridge boards:
	o 6G SATA Bridge Board (Default)
	One compute module power docking board
Air Duct	One transparent air duct
Form Factor	10
Module Dimensions	L=592.8mm, W=177.5mm, H=40.8

1. The table only lists features that are unique to the compute module or different from the server board

1.2 Product Family Summary Chart

The following tables provides an overview of available Intel product codes for the Intel® S7200AP product family. Each line item identifies key features supported in the shipping Intel SKU. Additional order code information and full product descriptions for each option are provided in later sections.

Table 3. Intel Server Board Product Summary

Intel Product Code	Development Status	Packaged quantity	# of CPU sockets	# of DIMM Slots	# of Riser Slots	Onboard RJ45 LAN ports	# of SATA ports (6 Gb)	SATA SW RAID Support	Liquid Cooling Support
Server Board only									
BBS7200APL	Production	10 pack	1	6	2	2 (1 GbE)	10	Yes	Yes
BBS7200AP	Production	10 pack	1	6	2	2 (1 GbE)	10	Yes	No

Table 4. Intel Compute Module Product Summary

Intel Product Code	Development Status	Form Factor	Intel Server Board	Liquid Cooling Support
Compute Module				
HNS7200APL	Production	1U Module	S7200APL	Yes
HNS7200AP	Production	1U Module	S7200AP	No

Table 5. Server Chassis Product Family Summary

Intel Product Code	Development Status	Chassis Form Factor	Drive Form Factor	# of Drives	# of Power Supply Modules	Power Supply Rating	Rack Mount Rails Included
Chassis Only (KDK)							
H2312XXLR2	Production	2U	3.5"	12	2	2130W	Yes
H2216XXLR2	Production	2U	2.5"	16	2	2130W	Yes

• KDK = Knock Down Kit - Intel nomenclature defining a chassis only product

Additional Product Information

For additional information about this family of products or any of their supported accessories, refer to the following resources available at: http://www.intel.com/content/www/us/en/support/server-products/server-boards/single-socket-server-boards/intel-server-board-s7200ap-family.html

Table 6. Product Family Reference Collaterals

For this information or software	Use this Document or Software
	Intel® Server Board S7200AP Technical Product Specification
	Intel® Remote Management Module 4 (Intel® RMM4) and Integrated BMC User Guide
For in-depth technical information about this product	Intel® Remote Management Module 4 Technical Product Specification
family	Intel® Server System BIOS Setup Utility Guide
	Intel® Server Platform Firmware Specification Update
	Product Safety and Regulatory Compliance
For system integration instructions and service guidance	Intel® Server Board S7200AP Product Family and Intel® Compute Module HNS7200AP Service Guide
For server configuration guidance and compatibility	Intel® Server Configurator tool
For system power budget guidance	Intel® Server Board S7200AP Product Family and Intel® Compute Module HNS7200AP Power Budget Tool
For system firmware updates	System Update Package (SUP) – uEFI only
For system miniware updates	One-boot Flash Update Utility (OFU)
For a complete list of supported processors, memory, addin cards, and peripherals:	See Intel web site listed above

2. Server Building Block Configuration

Server building blocks within this Intel product family are offered to give Intel customers the option to design a custom chassis to support the stand alone Intel server board, or to configure one of the chassis only options with one to four server compute modules. Each building block component and optional accessory is purchased seperately.



Intel® Server Board S7200AP / APL

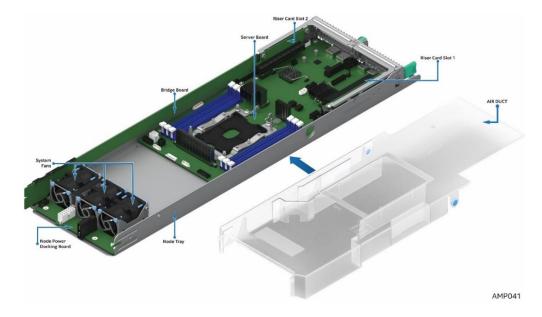


Intel® Compute Module HNS7200AP / APL



2U - Intel® Server Chassis H2000XXLR2 Family

See chapter 0 for available Intel accessories that can be added as options to the configured server.



2.1 Intel® Server Board S7200AP Product Family SKUs

Intel Product Code (iPC)	Order Information	Product Description	Product Type
iPC - BBS7200APL	MM# - 950090 UPC - 735858322874 EAN - 5032037090124 MOQ - 10 Packaged Gross Weight 12.9kg Un-packaged Net Weight 7.6kg	Intel® Server Board S7200AP • Board Dimensions: 6.8" W x 14.2" L (172.72mm W x 360.68mm L) • 1 Processor Slot – Intel Xeon® Phi™ series only • 6 DIMM Slots supporting DDR4 memory • 2 PCIe* 3.0 capable add-in / riser card slots • 2 RJ45 1GbE Networking Ports • Liquid Cooling Support Box includes: one server board	Server Board only Building block option Spare FRU
iPC – BBS7200AP	MM# - 942367 UPC - 735858322881 EAN - 5032037090131 MOQ - 10 Packaged Gross Weight 12.9kg Un-packaged Net Weight 8.1kg	Intel® Server Board S7200AP • Board Dimensions: 6.8" W x 14.2" L (172.72mm W x 360.68mm L) • 1 Processor Slot – Intel Xeon® Phi™ series only • 6 DIMM Slots supporting DDR4 memory • 2 PCIe* 3.0 capable add-in / riser card slots • 2 RJ45 1GbE Networking Ports • Box includes: one server board	Server Board only Building block option Spare FRU

2.2 Intel® Compute Module Product Family SKUs

The product tables found in this section provide order code information and detailed descriptions for each available Intel Conpute Module option. The lower sections of each table identify:

- The ship along components of the specified chassis product code (product BOM)
- Required Items Hardware required to be installed to the base system to achieve basic functionality using the default system feature set
- Optional Accessories Some of the available accessories which can be installed to enhance the basic feature set of the server board / chassis. Additional accessories can be found in Chapter 0

NOTES:

- Each required item and optional accessory is sold seperately from the specified Intel server building block
- Items identifed as iPC (Intel Product Code), are an orderable building block option, accessory or spare FRU
- In an effort to provide the complete product bill of materials, the ship along components list in each product table will include items identified by description and by **iPN** (Intel Part Number). The iPN information is provided for reference only. These components are **not** orderable as a spare or accessory.

Intel Product Code (iPC):

HNS7200AP



Order Code Information:

MM# - **942355**

UPC - 735858322898

EAN - 5032037090148

MOQ - 1

Product Type: Produciton Compute Module

Module dimensions: L=592.8mm, W=177.5mm, H=40.8

Packaged Gross Weight: 4.55kg Un-packaged Net Weight: 3.05kg

Packaging Dimensions: 720x272x162mm

Product Definition and Configuration Requirements

Intel product code **HNS7200AP** is a fully assembled compute module that includes the following components:

- (1) Intel Server Board S7200AP iPC BBS7200AP
- (3) System fans iPC FXX4056DRFAN2
- (1) Slot 1 Riser Card iPC FHW1UAP16RISER2
- (1) Slot 2 Riser Card iPC FHW1U20APRISER
- (1) I/O Bridge Board iPC FHWAPBGB
- (1) Power Docking Board iPC FH2000NPBAP
- (1) 130mm 2x7 Fan Assembly Cable iPN H62040-00x
- (1) 140mm 2x3 Internal Power Cable iPN H62040-00x
- (1) Air Duct iPN H72964-00x
- (1) Plastic Cover iPN H35490-00X
- (1) Processor Heat Sink iPC AXXAPHS

Required Items - Sold Separately:

- 1 Intel® Xeon® Phi™ Processor Series
- ECC DDR4 memory (RDIMM or LRDIMM)

Optional Intel Accessories - Sold Separately:

- AXX2PFABKIT Intel® Omnipath 2-port upgrade kit
- AXXRMM4LITE Remote KVM Upgrade Module
- AXXRMM4 Remote KVM Upgrade module + Dedicated Management Port
- AXXTPME5 TPM 2.0 Module for server systems

See Chapter 3 for all available accessory options.

Intel Product Code (iPC):

HNS7200APL



Order Code Information:

MM# - 950091

UPC - 735858322904

EAN - 5032037090155

MOQ - 1

Product Type: Production Compute Module

Module dimensions: L=592.8mm, W=177.5mm, H=40.8

Packaged Gross Weight: 4.5kg Un-packaged Net Weight: 3kg

Packaging Dimensions: 720x272x162mm

Product Definition and Configuration Requirements

Intel product code **HNS7200AP** is a fully assembled compute module that includes the following components:

- (1) Intel Server Board S7200AP iPC BBS7200APL
- (3) System fans iPC FXX4056DRFAN2
- (1) Slot 1 Riser Card iPC FHW1UAP16RISER2
- (1) Slot 2 Riser Card iPC FHW1U20APRISER
- (1) I/O Bridge Board **iPC FHWAPBGB**
- (1) Power Docking Board iPC FH2000NPBAP
- (1) 130mm 2x7 Fan Assembly Cable iPN H62040-00x
- (1) 140mm 2x3 Internal Power Cable iPN H62040-00x
- (1) Air Duct iPN H72964-00x
- (1) Plastic Cover iPN H35490-00X
- (1) Processor Heat Sink **iPC AXXAPHS**

Required Items - Sold Separately:

- 1 Intel® Xeon® Phi™ Processor Series
- ECC DDR4 memory (RDIMM or LRDIMM)

Optional Intel Accessories - Sold Separately:

- AXX2PFABKIT Intel® Omnipath 2-port upgrade kit
- AXXRMM4LITE Remote KVM Upgrade Module
- AXXRMM4 Remote KVM Upgrade module + Dedicated Management Port
- AXXTPME5 TPM 2.0 Module for server systems

See Chapter 3 for all available accessory options.

2.3 Intel® Server Chassis H2000XXLR2 Product Family SKUs

The product tables found in this section provide order code information and detailed descriptions for each available 2U Intel server chassis building block option. The lower sections of each table identify:

- The ship along components of the specified chassis product code (product BOM)
- Required Items Hardware required to be installed to the base system to achieve basic functionality using the default system feature set
- Optional Accessories Some of the available accessories which can be installed to enhance the basic feature set of the server board / chassis. Additional accessories can be found in Chapter 0

NOTES:

- Each required item and optional accessory is sold seperately from the specified Intel server building block
- Items identifed as iPC (Intel Product Code), are an orderable building block option, accessory or spare FRU
- In an effort to provide the complete product bill of materials, the ship along components list in each product table will include items identified by description and by **iPN** (Intel Part Number). The iPN information is provided for reference only. These components are **not** orderable as a spare or accessory.

Intel Product Code (iPC): H2312XXLR2

2U - 12 x 3.5" front mount hot swap drives

Order Code Information:

MM# - **942352**

UPC - 00735858316729

EAN - 5032037086981

MOQ - 1

Product Type: Chassis only

Chassis Form Factor: 2U rack mount with support for upto 4 Compute Modules

Chassis dimensions: L=771mm, W=438mm, H=86.9mm

Packaged Gross Weight: 28.32 Kgs, 62.434 Lbs. Un-packaged Net Weight: 19.97 Kgs, 44.026 Lbs.

Outer Box Dimensions: L=984mm, W=578mm, H=266mm

Product Definition and Configuration Requirements

Intel product code **H2312XXLR2** includes the following components:

- (1) 12 x 3.5" Hot swap backplane iPC FHW12X35HS12G
- (12) 3.5" hot swap drive trays iPC FXX35HSCAR
- (1) Front Panel / Rack Handle Assembly iPC FH2000FPANEL2
- (2) 2130W Power supply modules iPC **FXX2130PCRPS**
- (1) Power Distribution board assembly iPC FXXCRPSPDB2
- (1) Rack Mount Rail Kit iPC AXXELVRAIL
- (1) Attention Doc insert iPN H46721-00x

- Upto 4 of the following
 - Intel® Compute Module HNS7200AP or

Required Items - Sold Separately:

- Intel® Compute Module HNS7200APL
- AC Power Cords

Optional Intel Accessories - Sold Separately:

- iPC **A2UBEZEL** Lockable front system bezel
- Storage Drives

See Chapter 3 for all available accessory options.

Intel Product Code (iPC):

H2216XXLR2



2U - 16 x 2.5" front mount hot swap drives

Order Code Information:

MM# - **942353**

UPC - 0073585831673

EAN - 5032037086998

MOQ - **1**

Product Type: Chassis only

Chassis Form Factor: 2U rack mount with support for upto 4 Compute Modules

Chassis dimensions: L=733mm, W=438mm, H=86.9mm

Packaged Gross Weight: 29.12 Kgs, 64.198 Lbs. Un-packaged Net Weight: 19.54 Kgs, 43.078 Lbs.

Outer Box Dimensions: L=984mm, W=578mm, H=266mm

Product Definition and Configuration Requirements

Intel product code **H2216XXLR2** includes the following components:

- (1) 16 x 2.5" Hot swap backplane iPC **FHW16X25HS12G**
- (12) 2.5" hot swap drive trays iPC FXX25HSCAR2
- (1) Front Panel / Rack Handle Assembly iPC FH2000FPANEL2
- (2) 2130W Power supply modules iPC FXX2130PCRPS
- (1) Power Distribution board assembly iPC **FXXCRPSPDB2**
- (1) Rack Mount Rail Kit iPC AXXELVRAIL
- (1) Attention Doc insert iPN H46721-00x

Required Items - Sold Separately:

- Upto 4 of the following
 - Intel® Compute Module HNS7200AP or
 - Intel® Compute Module HNS7200APL
- AC Power Cords

Optional Intel Accessories – Sold Separately:

- iPC **A2UBEZEL** Lockable front system bezel
- Storage Drives

See Chapter 5 for all available accessory options.

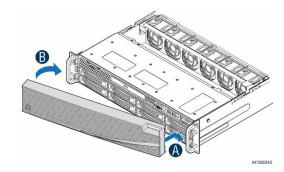
3. Accessory Options

The following sections identify available accessory kits supported by the Intel® S7200AP product family.

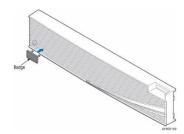
3.1 2U System Locking Front Bezel Accessory Kit

The optional front bezel is made of Black molded plastic and uses a snap-on design. When installed, its design allows for maximum airflow to maintain system cooling requirements. The front bezel includes a keyed locking mechanism which can be used to prevent unauthorized access to installed storage devices and front I/O ports.

Intel Product Code	Order Information	Product Description	Product Type
iPC – A2UBEZEL	MM# – 918086 UPC – 735858241137 EAN – 5032037035880 MOQ – 1	2U Front Bezel Accesory Kit Kit Includes: (1) 2U locking bezel (1) Front Panel Window Insert (1 Set) Bezel branding inserts – two ID badges, one wave (1 Set) Keys	2U Accessory Kit



The face of the bezel assembly includes snap-in identification badge options and a wave feature option to allow for customization.



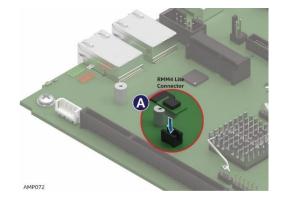
3.2 Remote Management KVM Support Options

The integrated baseboard management controller has support for advanced management features which are enabled when an optional Intel® Remote Management Module 4 or RMM4 Lite is installed. The Intel RMM4 add-on offers convenient, remote KVM access and control through LAN and internet. It captures, digitizes, and compresses video and transmits it with keyboard and mouse signals to and from a remote computer. Remote access and control software runs in the integrated baseboard management controller, utilizing expanded capabilities enabled by the Intel RMM4 hardware.

Key Features of the RMM4 add-on are:

- KVM redirection from the server board NICs used for management traffic; up to two KVM sessions
- Media Redirection The media redirection feature is intended to allow system administrators or users to mount a remote IDE or USB CDROM, floppy drive, or a USB flash disk as a remote device to the server. Once mounted, the remote device appears just like a local device to the server allowing system administrators or users to install software (including operating systems), copy files, update BIOS, or boot the server from this device.

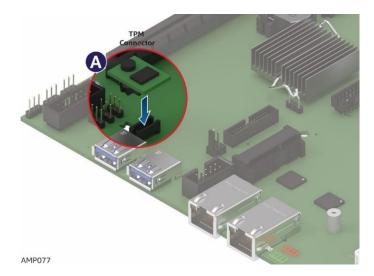
Intel Product Code	Order Information	Product Description	Product Type
iPC – AXXRMM4LITE	MM# – 911660 UPC – 00735858219297 EAN – 5032037014946 MOQ – 1	Intel® Remote Management Module 4 Lite Kit Includes: (1) RMM4 Lite module	Accessory Kit
iPC – AXXRMM4LITE2	MM# – 946514 UPC – 007358307413 EAN – 5032037080750 MOQ – 1	Intel® Remote Management Module 4 Lite 2 Kit Includes: (1) RMM4 Lite 2 module	Accessory Kit



3.3 Intel® Trusted Platform Module (TPM) Security Option

The Intel®Trusted Platform Module (TPM) is a hardware-based security device that addresses the growing concern on boot process integrity and offers better data protection. TPM protects the system start-up process by ensuring it is tamper-free before releasing system control to the operating system. A TPM device provides secured storage to store data, such as security keys and passwords. In addition, a TPM device has encryption and hash functions. The Intel® TPM module implements TPM as per TPM PC Client specifications revision 2.0 by the Trusted Computing Group (TCG).

Intel Product Code	Order Information	Product Description	Product Type
iPC – AXXTPME6	MM# – 947921 UPC – 00735858314534 EAN – 5032037086059 MOQ – 1	Intel® Trusted Platform Module (TPM) 2.0 Kit Includes: (1) TPM Module for server systems	Accessory Kit

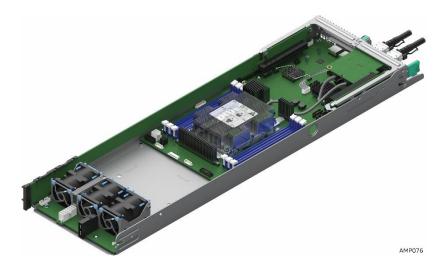


3.4 Intel® Omni-path Host Fabric Interface Support Option

The Intel® Server Board S7200AP supports the bootable Intel® Xeon Phi™ processor (KNL-F) with integrated Intel® Omni-Path Host Fabric Interface (HFI). These processors have two 25 GB/s fabric I/O ports with up to 50 GB/s bi-directional peak total bandwidth.

Intel's Fabric Through (IFT) Carrier kit allows external access to the Intel® Omni-Path Host Fabric Interface (HFI) socket of the processor. The external connection access is accomplished through use of two QSFP+28 style connections.

Intel Product Code	Order Information	Product Description	Product Type
iPC – AXX2PFABKIT		Intel® Fabric Through (IFT) Carrier Kit	
Intel® Christ Path Fabric Processor Cable Fabric Christ Christ Sidehard Cable Fabric Sidehard Cable	MM# - 945579 UPC - 735858322911 EAN - 5032037090162 MOQ - 1	Kit Includes: (1) KNL Fabric Carrier – iPN H53248-00x (1) 2 Port IFP card (1) 2 Port IFP cable (1) Sideband cable	Accessory Kit



3.5 S7200AP Video Debug Cable Option

The S7200AP Video Debug Cable Option is a VGA video cable that connects to a header on the S7200AP board which can be routed to a connector bracket on the rear node panel when used with the HNS7200AP product. The cable is intended for debug use when deploying S7200AP-based systems and is not intended for normal product operation.

Intel Product Code	Order Information	Product Description	Product Type
iPC – AXXADPVIDCBL	MM# - 953982 UPC - 735858328081 EAN - 5032037094320 MOQ - 1	S7200AP Video Debug Cable Option Kit Includes: (1) VGA video cable (2) Rear panel mounting bracket for VGA port	Accessory Kit

4. Spare and Replacement Parts (FRUs)

System integrators and distributors may choose to hold additional stock of individual system components. Intel makes available the following Spare and Replacement Parts (FRUs) compatible with the specified Intel server family.

Intel Product Code	Order Information	Product Description	Product Type
iPC – FXX4056DRFAN2	MM# – 935566 UPC – 735858288439 EAN – 5032037067751 MOQ – 1	40x56mm Dual Rotor Fan spare	Spare FRU
iPC – FXX2130PCRPS	MM# – 948196 UPC – 00735858311939 EAN - 5032037084062 MOQ – 1	2130W AC Common Redundant Power Supply 80Plus Platinum-Efficiency	Spare FRU
iPC – FHW12X35HS12G	MM# – 935567 UPC – 735858288446 EAN – 5032037067768 MOQ – 1	12Gb SAS spare 12 x 3.5" backplane for H2000XXLR2 Chassis family	Spare FRU

Intel Product Code	Order Information	Product Description	Product Type
iPC – FHW16X25HS12G	MM# – 935573 UPC – 735858288453 EAN – 5032037067775 MOQ – 1	12GB SAS spare 16 x 2.5" backplane for H2000XXLR2 Chassis family	Spare FRU
iPC – FH2000NPBAP	MM# – 954595 UPC – 7358583332705 EAN – 5032037097734 MOQ – 1	Spare Node Power Board for H2000XXKR2 Chassis with the HNS7200AP Compute Module	Spare FRU
iPC – FXXCRPSPDB2	MM# – 935576 UPC – 735858288460 EAN – 5032037067782 MOQ – 1	Spare Power Distribution Board Module including 2 boards, cables, a bus pair and supporting bracket, etc. for Common Redundant Power Supply 1600W of H2000XXKR2 chassis	Spare FRU
iPC – FH2000FPANEL2	MM# – 935578 UPC – 735858288415 EAN – 5032037067737 MOQ – 1	Spare front control panel kit(2 mini-front panel boards and rack handle assembly) for H2000KR2 Chassis family	Spare FRU
iPC – FXX25HSCAR2	MM# – 937542 UPC – 735858289405 EAN – 5032037068383 MOQ – 8	Spare 2.5" hot swap drive carriers	Spare FRU

Intel Product Code	Order Information	Product Description	Product Type	
iPC – FXX35HSCAR	MM# - 936192 UPC - 00735858289412 EAN - 5032037068390 MOQ - 8	Spare 3.5" hot swap drive carriers	Spare FRU	
iPC – AXXELVRAIL	MM# – 920970 UPC – 00735858244367 EAN – 5032037038980 MOQ – 1	Value Rail Kit, half extension, extended inner slide member	Spare FRU	
iPC – FPWRCABLENA	MM# – 879287 UPC – 735858181129 EAN – 5032037015738 MOQ – 1	North American Power Cord Spare	Spare FRU	

5. Extended Warranty

Image	Order Information	Description
	iPC – SVCEWHWSY MM# – 923113 MOQ – 1	Extended Warranty for complete system (1x Intel® Server Chassis H2000G + 4x Intel® Compute Module HNS7200AP), Single.
Stages there or Companion Committee Charges, Eag. (Symmetric Michiga Waterschool is a realized title? There are Companion of Committee Charges Pages to some organisms train for the colors and the same organisms Pages to some organisms train for the colors and the same organisms (Symmetric Michigan Charges)	iPC - SVCEWHWB MM# – 914905 MOQ – 1	Extended Warranty for single node (1x Intel® Compute Module HNS7200AP), Single
Expension: Distance Common of Change Exp. Expension: DEClays Brace Control is analysis test? There Companies Control Change I have a control to the Control Control Control Control Control I have a control Control Control Control Control Control I have a control Control Control Control Control Control I control Control Control I control Control I control Control I cont	iPC - SVCEWDPBD MM# – 911294 MOQ – 1	Extended warranty for the mainboard only (for use with 3 rd party chassis; applies to board only SKUBBS7200AP)

Glossary of Terms

A list of Acronyms and Terms used throughout this document

Acronym or Term	Definition	Acronym or Term	Definition
BIK	B aseboard I n K nock-Down-Kit – Integrated System	QSFP	Quad Small Form factor Pluggable
CRPS	Common Redundant Power Supply	RAID	Redundant Array of Independent Drives
EAN	International Article Number (Barcode)	Required Option	Hardware that must be added to the shipping configuration for the system to operate
EMI	Electromagnetic Interference	RMFBU	RAID Maintenance Free Backup Unit
ESRT2	Intel® Embedded Server RAID Technology 2	RMM4 Lite	Intel® Remote Management Module 4 Lite Activation key
FDR Infiniband	Fourteen Data Rate Infiniband	ROC	RAID on Chip
FRU	Field Replaceable Unit	RSTe	Intel® Rapid Stroage Technology
GPGPU	General Purpose computing on Graphics Processing Unit	SAS	Serial Attached SCSI
iPC	Intel Product Code	SATA	Serial ATA
iPN	Intel Product Number	SFP	Small Form factor Pluggable
LCP	Intel® Local Control Panel		
JBOD	Just a bunch of drives		
KDK	Knock-Down-Kit – (Chassis only product)	SKU	Stock Keeping Unit
KVM	Keyboard / Video / Mouse	SSD	Solid State Drive
MM#	Master Material order number	UPC	Universal Product Code (Barcode)
MOQ	Mimimum Order Quantity		
NVMe	NVM Express – based on Non-Volatile Memory Host Controller Interface Specification (NVMHCI)		
Optional Accessory	Hardware that can be added to the system to enhance the default feature set of the shipping configuration		
PCBA	Printed Cricuit Board Assembly		

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